

REMARKS

The present Amendment is in response to the Office Action mailed September 22, 2004, in the above-identified application. Enclosed herewith is a petition requesting a three month extension of time for resetting the deadline for responding to the Office Action from December 22, 2004, to and including March 22, 2005.

As an initial matter, Applicants acknowledge and appreciate the Examiner's indication that claims 2 and 8 contain allowable matter. Specifically, the Examiner asserted that claims 2 and 8 would be allowable if rewritten in independent form to include all of the limitations of the base claim and any intervening claims.

Enclosed herewith is a Supplemental Information Disclosure Statement that includes a copy of the reference entitled "Multi-chip Module Technologies and Alternatives, the Basics." Applicants respectfully request that the reference be made of record and considered in the present application.

In the Office Action, the Examiner rejected claim 6 under 35 U.S.C. §112, second paragraph, as being indefinite. In response, Applicants have amended claim 6 to change "said second microelectronic assembly" to --said second microelectronic element--. In view of the above-noted amendment, claim 6 is now deemed to satisfy the requirements of 35 U.S.C. §112, second paragraph, and as is otherwise allowable.

Applicants note that the Abstract of the Disclosure has been amended to reflect the changes made to claim 1.

In the Office Action, the Examiner rejected claims 1 and 3-6 under 35 U.S.C. §102(b) as being anticipated by U.S. Patent No. 4,818,728 to Rai et al. Referring to FIGS. 1A - 1C thereof, Rai discloses a method of electrically interconnecting two semiconductor devices including a first semiconductor device

1 having electrodes 2, an insulating layer 3 and metal studs 4 made of copper or gold. A second semiconductor device 1' includes electrodes 2', insulating layer 3' and solder deposits 5 made of, for example, Sn, Pb or In. Referring to FIG. 1C, during assembly, the metal studs 4 of the first semiconductor device 1 are aligned with the electrodes 2' and solder deposits 5 of the second semiconductor device 1'. The solder deposits are heated and the metal studs 4 are pressed into the metal solder deposits 5 for creating an electrical interconnection between the first semiconductor device 1 and the second semiconductor device 1'. As noted above, independent claim 1 has been amended to recite "at least one flexible lead extending between and electrically interconnecting said first and second microelectronic elements." Applicants respectfully assert that claim 1 is unanticipated by Rai, *inter alia*, because the reference neither discloses nor suggests a microelectronic assembly including "at least one flexible lead extending between and electrically interconnecting said first and second microelectronic elements." Moreover, claim 1 now includes the "flexible lead" limitation that the Examiner indicated was patentable. For all of these reasons, claim 1 is unanticipated by Rai and is otherwise allowable. Claims 3-6 are unanticipated, *inter alia*, by virtue of their dependence from claim 1, which is unanticipated by the reasons set forth above.

The Examiner also rejected claims 1 and 3-7 under 35 U.S.C. §102(e) as being anticipated by U.S. Patent No. 6,379,982 to Ahn et al. Applicants respectfully assert that Ahn is not a valid prior art reference because Ahn has a filing date of August 17, 2000, which is later than the earliest priority date (March 15, 2000) of the present application. Thus, Applicants respectfully assert that the Ahn reference should not be considered as prior art in the present application. As such,

claim 1 is unanticipated by Ahn and is otherwise allowable. Claim 1 is also unanticipated because Ahn neither discloses nor suggests the limitations recited in claim 1 including a microelectronic assembly having "at least one flexible lead extending between and electrically interconnecting said first and second microelectronic elements." Claim 2, which the Examiner indicated contains allowable matter, has been amended to be an independent claim having the limitations of original claim 1 incorporated therein. As such, Applicants respectfully assert that claim 2 is patentable over the prior art and is otherwise allowable.

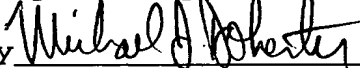
As it is believed that all of the rejections set forth in the Office Action have been fully met, favorable reconsideration and allowance are earnestly solicited.

If, however, for any reason the Examiner does not believe that such action can be taken at this time, it is respectfully requested that he telephone Applicants' attorney at (908) 654-5000 in order to overcome any additional objections which he might have.

If there are any additional charges in connection with this requested Amendment, the Examiner is authorized to charge Deposit Account No. 12-1095 therefor.

Dated: March 22, 2005

Respectfully submitted,

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